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28. (Amended) A laminar mat as claimed in claim 1, the mat including a non-slip backing material attached thereto.

38. (Amended) A method as claimed in claim 32, the method further including the steps of:

including on one of said planar layers heat-activated adhesive means on a lamina of heat conductive material,

after removing the moulded tile from the mould, positioning backing material on said layer of the tile using alignment means to align the tile and backing material,

and activating the heat activated adhesive to bond the backing material to the tile.

40. (Amended) A method as claimed in claim 38 wherein said heat conductive material is aluminum foil.

41. (Amended) A method as claimed in claim 32 including the step of providing alignment means on the tile, said alignment means serving to align the backing material before activation of the adhesive.